



# SOT261-3

plastic leaded chip carrier; 28 leads; pedestal, 1.27 mm pitch,  
11.5 mm x 11.5 mm x 4.38 mm body

11 October 2018

Package information

## 1 Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	PLCC28
<b>Package type industry code</b>	PLCC28
<b>Package style descriptive code</b>	PLCC (plastic leaded chip carrier)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	112E08
<b>JEDEC package outline code</b>	MO-047
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	15-11-2001
<b>Manufacturer package code</b>	SOT261

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	11.43	11.505	11.58	mm
package width	11.43	11.505	11.58	mm
seated height	4.19	4.38	4.57	mm
nominal pitch	-	1.27	-	mm
actual quantity of termination	-	28	-	



2 Package outline

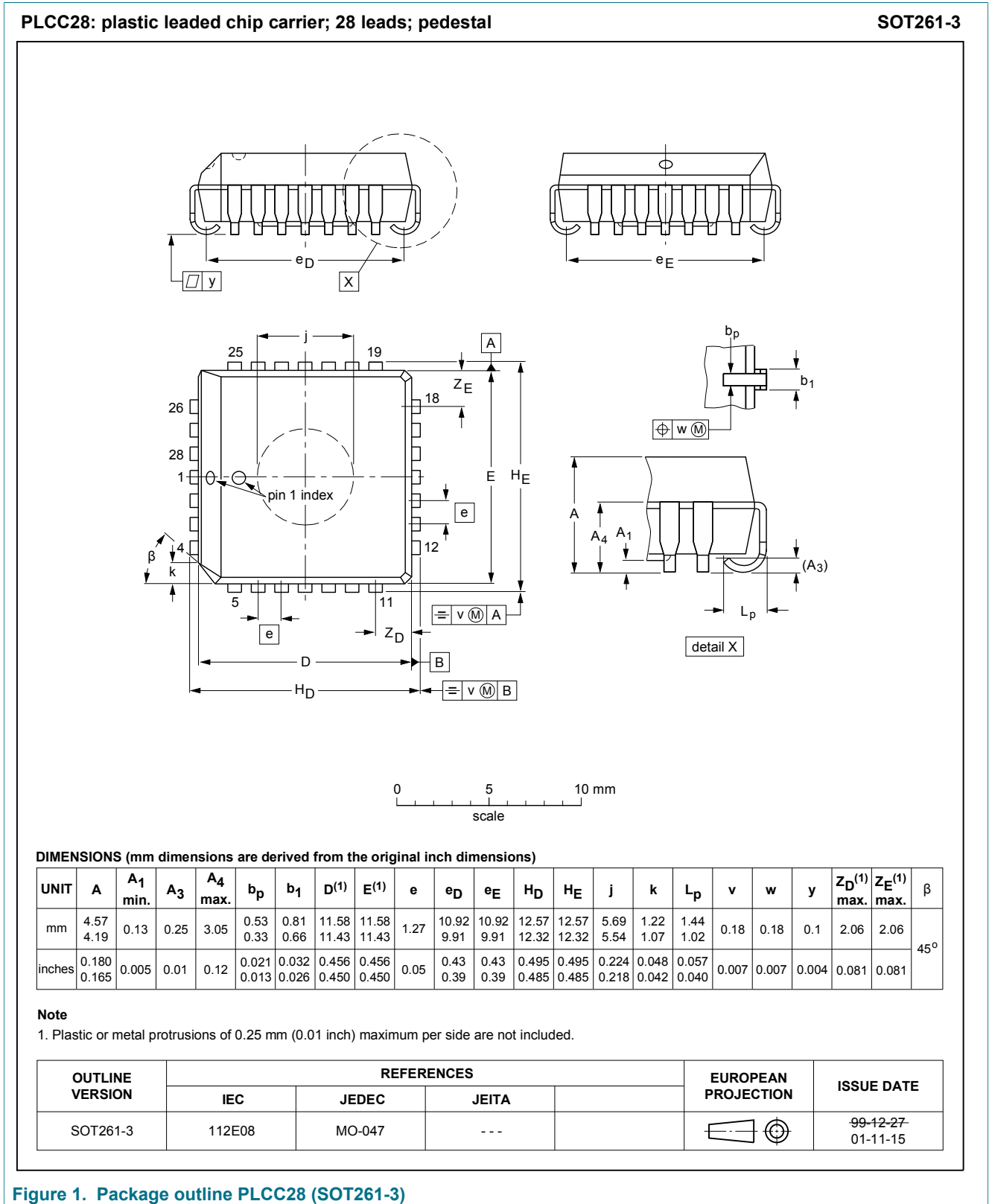
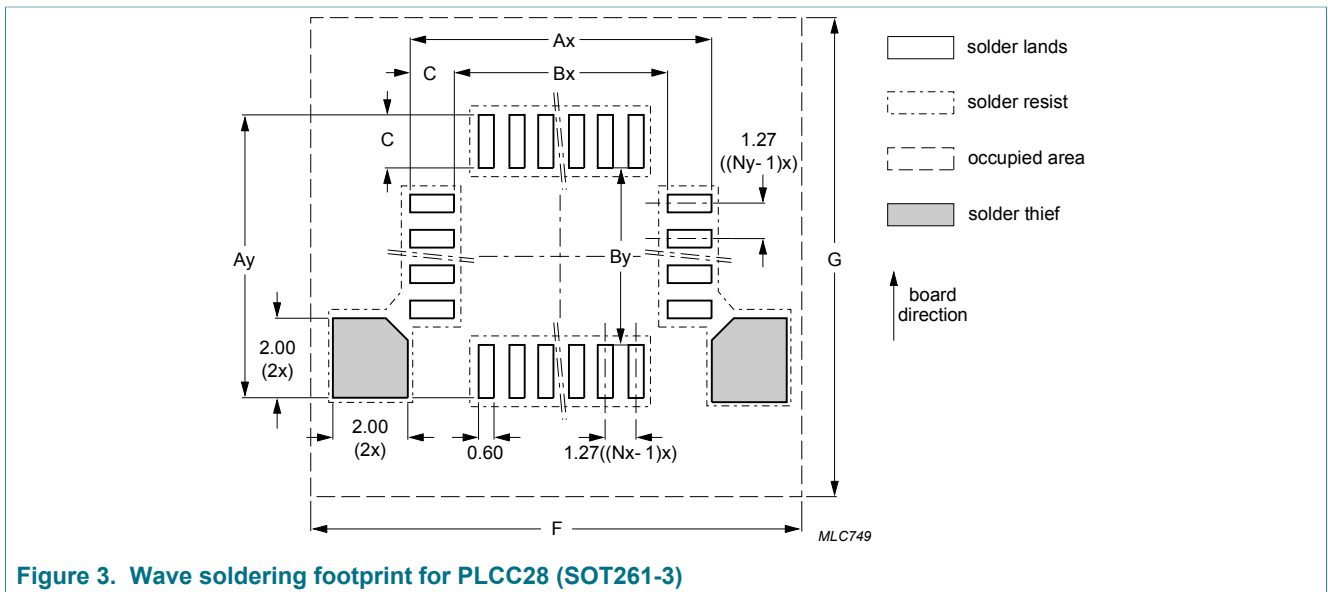
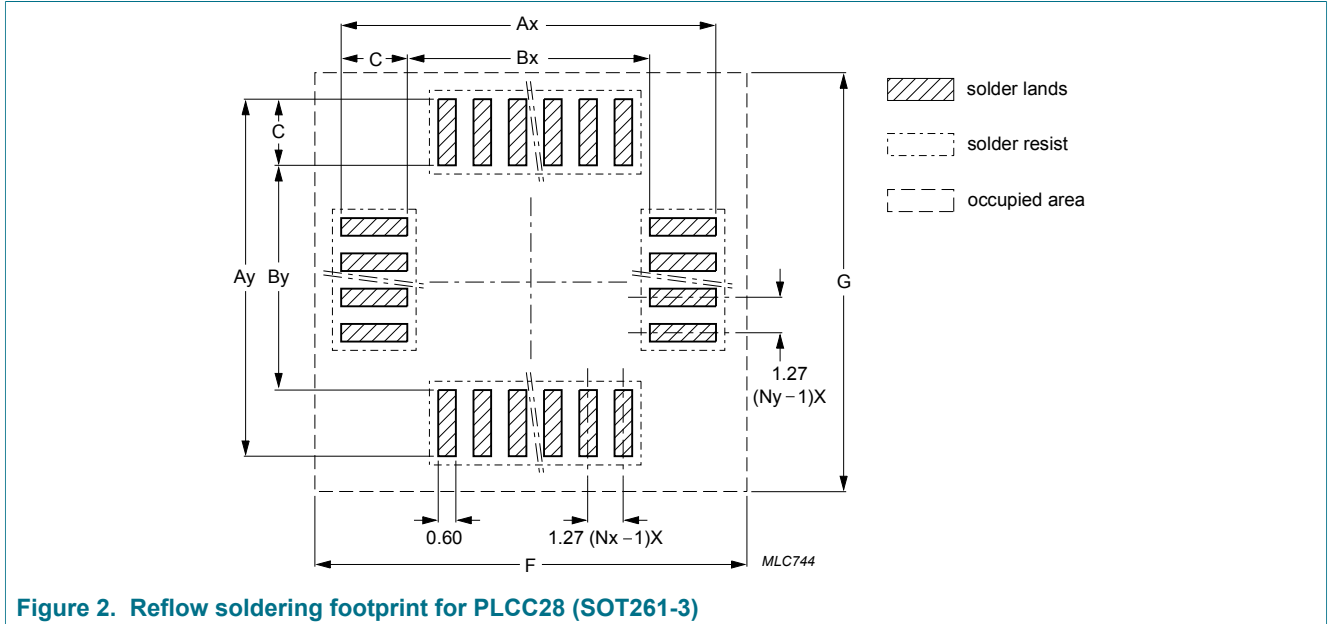


Figure 1. Package outline PLCC28 (SOT261-3)

### 3 Soldering



## 4 Legal information

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